EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	68544	CMP or "chemical mechanical polishing"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/21 08:29
L2	3343	polishing same pattern$4 same mask$4	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:30
L4	169	polishing same pattern$4 same correct$4	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:30
L5	3466	polishing and pattern and mask$4 and (peripheral or circumference)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:34
L7	122	polishing and pattern and mask$4 and (peripheral or circumference) and shadow	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:33
L10	258	polishing same pattern same (peripheral or circumference)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:35
L11	281	polishing same pattern same (peripheral or circumference or boundaries)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:36
L12	2	yu-tu-hao.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:36
L13	4	yu-tu-hao.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:37
L14	6	sun-pai-hsuan.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:37

L15	1	chen-yu-chia.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/21 08:37